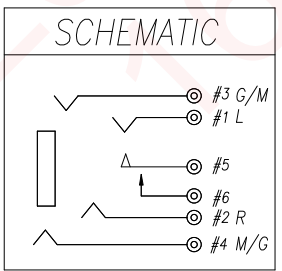
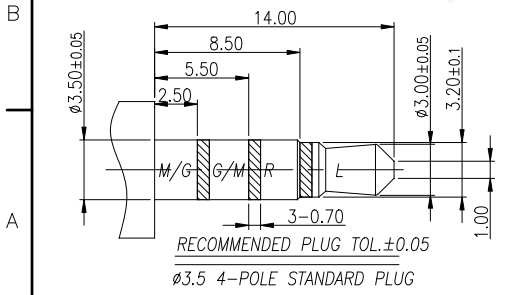
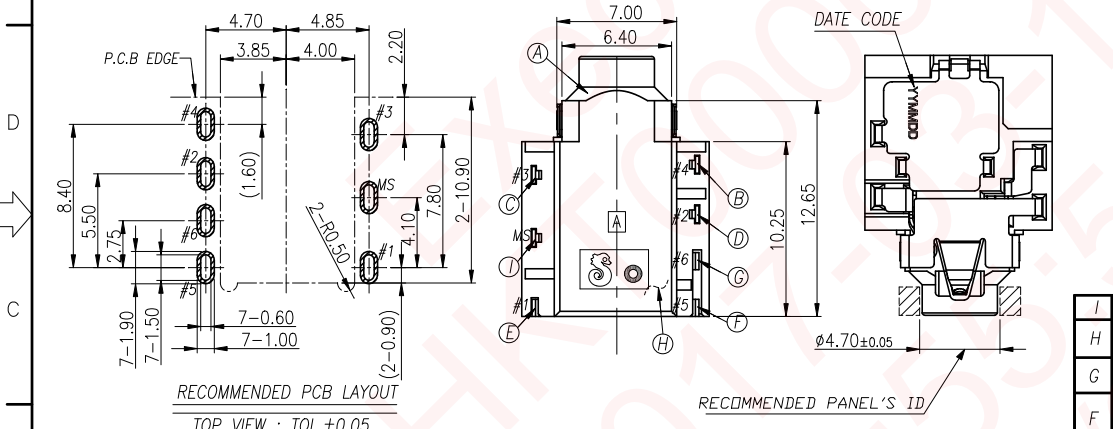
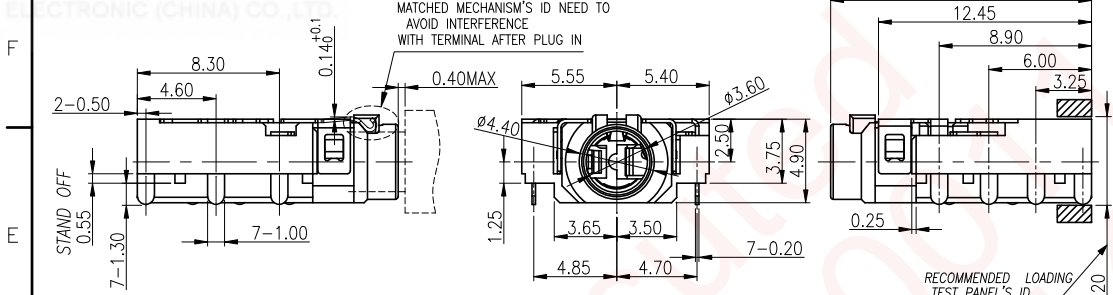


1 2 3 4 5 6 7 8

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T151225-5A/5B	Ming	2016.06.22



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
 - CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN.
 - INSERTION FORCE: 0.5 - 3Kg.
 - WITHDRAWAL FORCE: 0.5 - 3Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:

2SJ3095-110X11F
1:GOLD FLASH
2:Au 30u

I	SHELL	1	C5210-EH,0.2T	Ni 60u*Min.
H	SEPARATOR	1	LCP E130I+30%GF,UL94-V0	BLACK
G	MAKE TERMINAL	1	C5210-EH,0.2T	GOLD FLASH ON CONTACT AREA AND SOLDER PLATING OVER 50u Ni
F	TRANSFER TERMINAL	1	C5210-EH,0.2T	GOLD FLASH ON CONTACT AREA; Matte Sn100u ON SOLDER AREA; ALL OVER 50u Ni
E	TIP SPRING	1	SUS304-1/2H,0.2T	GOLD FLASH/Au 30u ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u Ni
D	RING A	1	C5210-EH,0.2T	GOLD FLASH/Au 30u ON CONTACT AREA
C	RING B	1	C5210-EH,0.2T	Matte Sn100u ON SOLDER AREA
B	EARTH	1	C5210-EH,0.2T	ALL OVER 50u Ni
A	BODY	1	PA4T+30%GF, UL94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:	ANGLES:	TITLE	3.5Ø PHONE JACK
X :±0.5	X :±2°	DWN	Ming PART NO. 2SJ3095-110X11F
X.X :±0.3	X.X :±1°	CHKD	Bruce SCALE 4:1 UNIT: mm
X.XX :±0.2		APVD	Lussen SIZE: A3 SHEET: 1 OF 1 REV: A
CUSTOMER COPY			